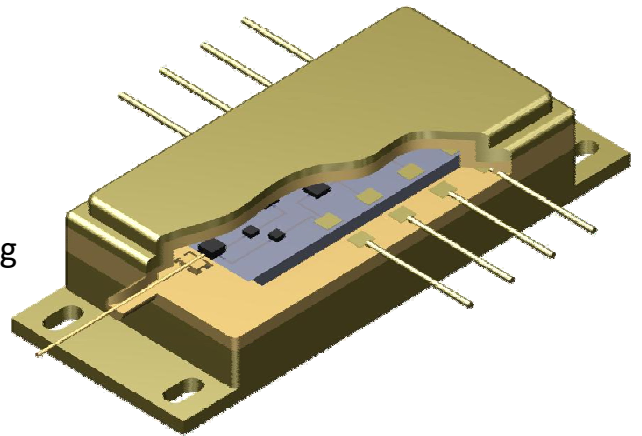


HERMETIC PACKAGING

As part of a continued effort to develop new and novel products and innovative solutions, Linden Photonics has patented an LCP package that can provide a functionally hermetic enclosure for optics and electronics. These custom designed packages enable the customer to have an inexpensive alternative to the typical metal or ceramic packages. In addition to being far less expensive our solution is easier to use than metal or ceramic packaging and 2 to 4 times lighter than conventional ceramic packaging; a serious advantage for any aerospace use.

FEATURES

- Eliminates Metallized Fiber
- No need for Optical Feedthroughs. No Threading
Fiber Through Holes
- Proprietary LCP Buffered Fiber Provides Near-Hermetic Optical Ports
 - Patent pending hermetic electrical port
 - Low Creep – Makes Complex Package Designs Possible
 - Radiation Resistant
 - Molded LCP Lid
 - Low Dielectric Constant and loss tangent to 100 GHz
 - Low CTE
 - Low Cost



APPLICATIONS

- Optical/Electrical Packaging
- Image Sensors
- LDMOS/CMOS
- MEMS
- RF Microwave

